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DIELECTRIC SOLUTIONS INTRODUCES NEW TECHNOLOGY AT ELECTRONIC CIRCUIT WORLD CONVENTION

--Innovative Products Open Up New Circuit Board Design Opportunities--

Anaheim, CA – Dielectric Solutions, LLC, an advanced materials company specializing in high performance glass fiber products, today announced the introduction of several innovative products at the Spring 2005 Electronic Circuit World Convention (ECWC) and IPC Expo in Anaheim, CA. The new products, all based on Dielectric Solutions' patented GlasFab[®] Process, were introduced to the printed circuit board industry for use in high performance multilayer circuitry, high speed digital applications and PTFE circuits for wireless and microwave applications.

“After a significant investment in an entirely new technology platform, we are very pleased to offer to the electronics industry what many consider to be a breakthrough in glass fabric reinforcement,” said John J. Kuhn, Vice President and Chief Technical Officer. “These new products give circuit designers what they have longed for – superior electrical properties combined with a flatter, thinner, smoother glass surface - that will improve dimensional stability, laser drilling performance, circuit reliability and allow for further circuit miniaturization.”

Patricia Goldman, Manager, Technical Service for Dielectric Solutions, presented the company's new technology platform at the ECWC convention. “We are extremely pleased with the positive response to these new products from circuit board designers

and producers all across the globe,” said Ms. Goldman. “Each of these products incorporate Dielectric Solutions' TwistFree[™] glass yarns that provide a thinner, smoother, more uniform circuit board substrate,” continued Ms. Goldman. Ms. Goldman also explained that the new process technology has allowed the company to improve the quality of the glass fabric in direct response to specific industry concerns about circuit reliability. The products can also be customized for specific application needs.

Dielectric Solutions is an advanced materials company specializing in light-weight glass fiber fabric, a key component of many advanced electronics products. The Company has developed a revolutionary, streamlined manufacturing process, the GlasFab[®] Process, which significantly reduces handling while increasing efficiency and product quality. The patented process produces a superior product that is not only thinner, stronger and more uniform but also exhibits improved electrical, thermal and mechanical properties as compared to other commercially available products. In addition to electronics, Dielectric Solutions' products are being sold into a wide range of high-tech composite applications in industries such as ballistics, aerospace, construction and petroleum. For more information, please contact Patricia Goldman at 724-284-9883, or email info@dielectricsolutions.com.

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